



REV.	ECN NO OR DESCRIPTION	REVISED	DATE

NOTES:

1. MATERIAL:

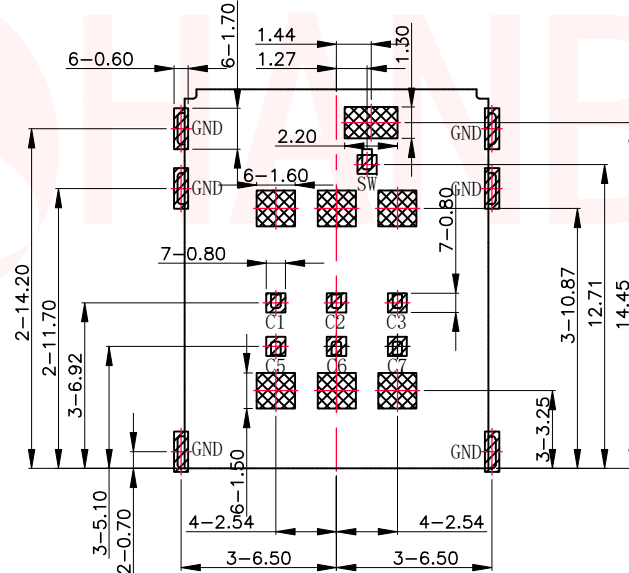
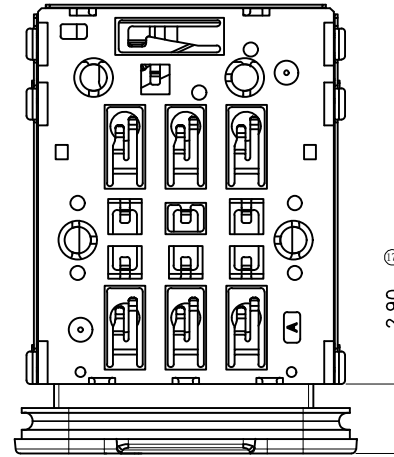
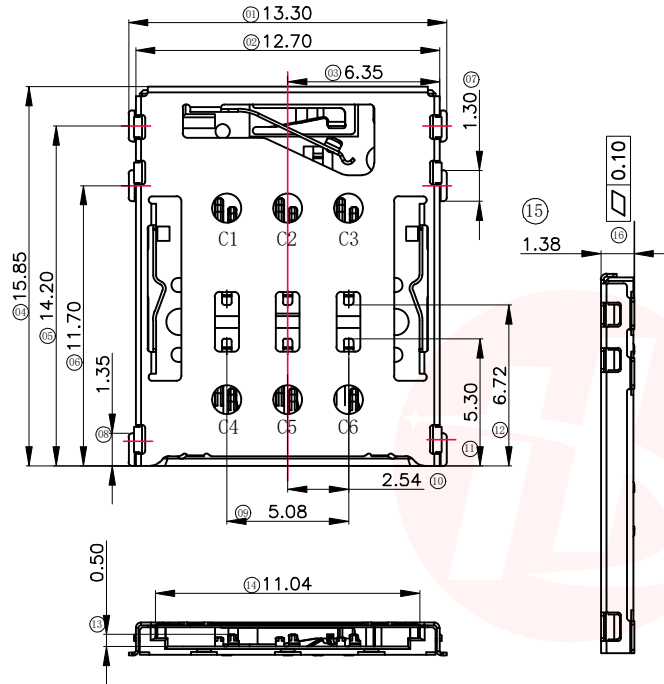
HOUSING: High Temperature Thermoplastic
Terminal: Copper Alloy
Shell: Stainless Steel

2. PLATING:

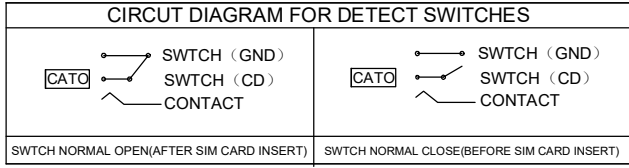
Terminal: 50u" Ni UNDERPLATED OVERALL
G/F PLATED ON CONTACT AREA AND SOLDER AREA
Shell: 30u" Ni UNDERPLATED OVERALL
G/F PLATED ON CONTACT AREA AND SOLDER AREA

3. TECHNICAL SPECIALITY:

RATED VOLTAGE: 30V AC MAX.
CURRENT RATING: 0.5A MAX.
INSULATION RESISTANCE: 1000MΩ MIN
CONTACT RESISTANCE: 50mΩ MAX
WITHSTANDING VOLTAGE: 500V AC FOR 1 MINUTES
INSERTION FORCE: 12N MAX
PUSH-OUT FORCE: 2N MIN
OPERATING TEMPERATURE: -40°C~+85°C Humidity 80% R.H MAX



PIIN/NO	ASSIGNMENT
C1	VCC
C2	RST
C3	CLK
SW	DetectSwitch
C5	GND
C6	VPP
C7	I/O

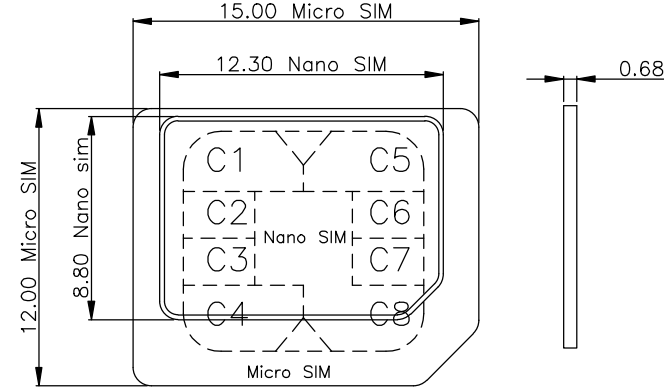


RECOMMENDED PCB LAYOUT

TOLERANCE: ± 0.05

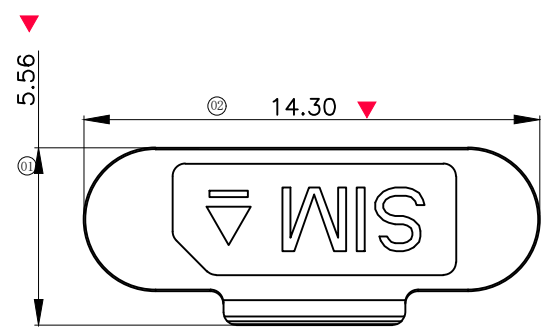
- SMT SOLDER AREA
- COPPER RESTRICTED AREA
- 1. TOUCH AREA OF CONTACT TIPS NO ELECTRICAL FUNCTION
- 2. NO FIRST PCB_LAYOUT CIRCUITS IN THE AREA

UNLESS OTHERWISE SPECIFIED TOLERANCES		东莞市汉博电子科技有限公司 DONGGUAN HANBO TECHNOLOGY CO., LTD	
DECIMALS:	ANGLES:	TITLE NANO SIM CARD 7PIN 1.38H PIN-PUSH	
X ±0.30	X ±2°	DWN	xiong PART NO. SNO-1470
X.X ±0.20	X.X ±1°	CHKD	lee SCALE:1:1 UNIT: mm
X.XX ±0.10		APVD	wang SIZE: A4 SHEET:10F 1 REV: A4
CUSTOMER COPY			



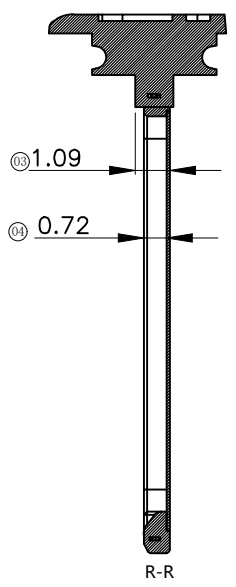
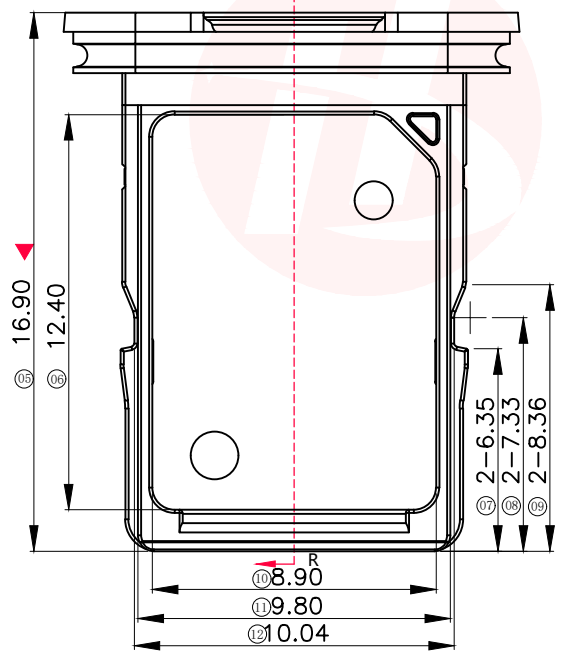
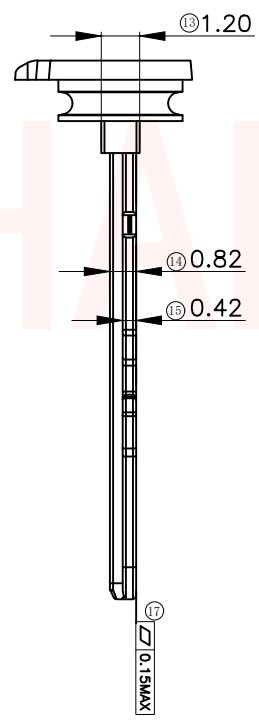
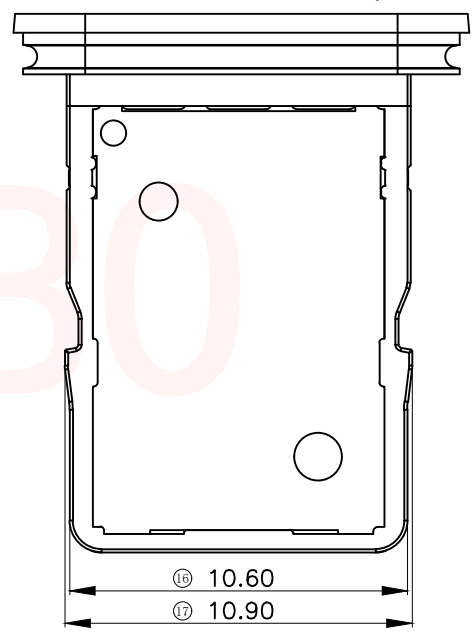


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NOTES:
 1. MATERIAL:
 HOUSING: Polycarbonate Black UL94V-0
 Terminal: Copper Alloy
 Shell: Stainless Steel
 2. Product should not shrink, dirty, deformation, lack of material
 3. Products must comply with RoHS requirements

如需防水需要装配防水圈



UNLESS OTHERWISE SPECIFIED TOLERANCES		东莞市汉博电子科技有限公司 DONGGUAN HANBO TECHNOLOGY CO., LTD			
DECIMALS:	ANGLES:	TITLE	NANO SIM 1.38H 防水卡托		
X : ±0.30	X : ±2°	DWN	xiong	PART NO. SNO-1470-KT-A	
X.X : ±0.20	X.X : ±1°	CHKD	lee	SCALE: 1:1	UNIT: mm
X.XX : ±0.10		APVD	wang	SIZE: A4	SHEET: 1 OF 1
CUSTOMER COPY					

A
B
C
D

A
B
C
D